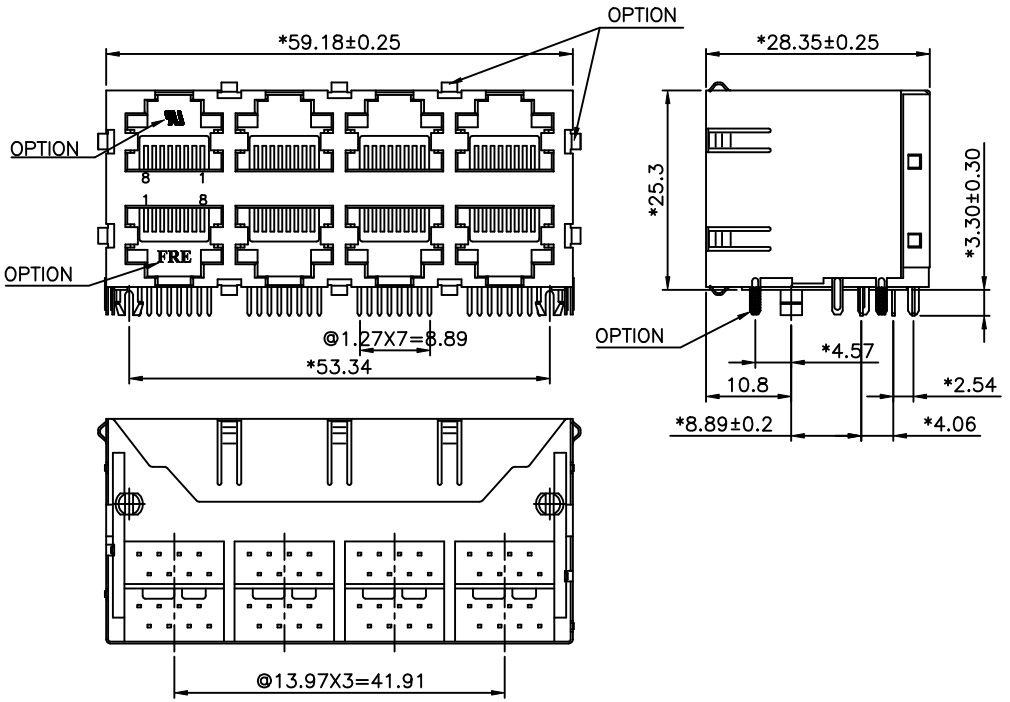
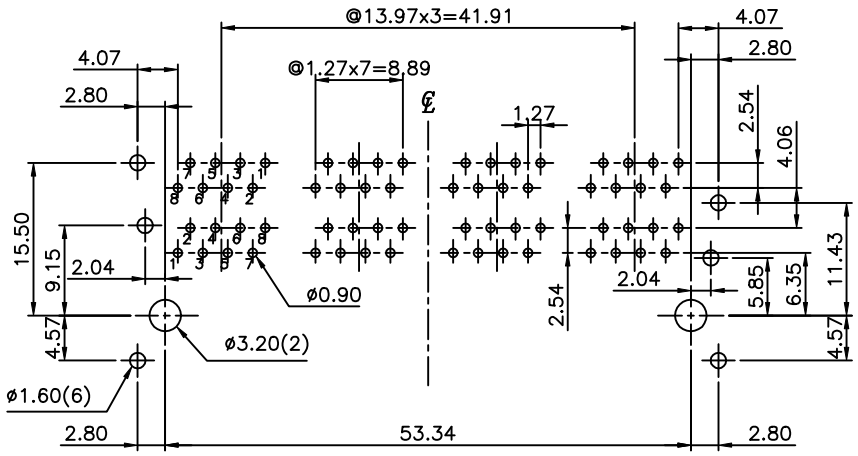
A1RFRD10

REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD
1		ADD P/N	JAMY 8/31/'05	
2		ADD P/N	JAMY 9/08/'05	





PC Board Layout Component Side Shown

Thickness=1.6mm

NOTES:

ELECTRICAL:
1. VOLTAGE RATING : 125 VAC RMS.
2. CURRENT RATING : 1.5 AMP.
3. CONTACT RESISTANCE : 50 MILLIOHMS MAX.
4. INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
5. DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

MECHANICAL:
1. HOUSING & INSERT MATERIAL : NYLON+30%.G.F UL94V-0.
2. CONTACT MATERIAL : PHOSPHOR BRONZE, t=0.35mm.
3. SHIELD MATERIAL : COPPER ALLOY, t=0.25mm.
4. PLATING : GOLD PLATING OVER NICKEL.
5. OPERATING LIFE : 750 CYCLES MIN.
6. PCB RETENTION PRE-SOLDER : 1 LB MIN.
7. PCB RETENTION POST-SOLDER: 10 LBS MIN.

ENVIRONMENTAL:
1. STORAGE : -40°C TO +85°C.
2. OPERATION: -40°C TO +85°C.
3. WAVE SOLDERING TEMPERRATURE: 255~265°C (5~10 SECONDS)

MATES WITH MODULAR PLUG CONFORMING TO
FCC PART 68, SUBPART F.
CUL FILE NO. E163191

ROHS PART NUMBER: E5908-XXCXXX-L

1-W/O TABS
2-W/ TOP TABS
3-W/ SIDE TABS
4-W/ TOP&SIDE TABS
5-W/ TOP&BOTTOM&SIDE TABS

1- 3u" 2- 6u" 3-15u"
4-30u" 5-50u"

10-FRONT PEG 4.57,W/O PANEL STOP,W/O LOGO. (1)
15-FRONT PEG 4.57,W/O PANTEL STOP,W/FRE&UL LOGO.
1E-FRONT PEG 4.57,W/O PANTEL STOP,W/FRE W/O UL LOGO. (2)

T- Tin V- Nickel Q- GOLD
J- W/NICKEL PLATED WITH TINNED GROUNDING PEG

MM (INCH)	DFTO YAN	DATE 04/27/05'	FULL RISE ELECTRONIC CO., LTD
TOLERANCES EXCEPT AS NOTED	CHKD SHIMMY	DATE 2005/09/08	
MM .0 ±0.2 ± .00 ±0.15 ± .000 ±0.075 ±	MFO	DATE	TITLE STAMPED PIN III STACKED GANGED JACK, 2X4
	APPVL LUSHENG	DATE 2005/09/08	
ANGLES ± 0.5	MATERIAL :		DRAWING NO. GE593B51-LA SIZE A3 REV 2
THIRD ANGLE PROJECTION	QT'Y :		/PART NO. SEE NOTE
DETACHED LISTS	FINISH :		DO NOT SCALE DRAWING SHEET 1 OF 1
	SCALE : 1.5 : 1		

8 7 6 5 4 3 2 1

H G F E D C B A